### 501880412 04/06/2012

#### PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Ying-Chou Cheng	04/06/2010
Cheng-Lung Tsai	04/07/2010
Tsong-Hua Ou	04/02/2010
Cheng Kun Tsai	04/02/2010
Ru-Gun Liu	04/02/2010
Wen-Chun Huang	04/06/2010

#### **RECEIVING PARTY DATA**

Name:	Taiwan Semiconductor Manufacturing Company Ltd.	
Street Address:	No. 8, Li-Hsin Road 6	
Internal Address:	Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

#### PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	12712665	

## **CORRESPONDENCE DATA**

**Fax Number**: (214)200-0853 **Phone**: 214-651-5000

Email: ipdocketing@haynesboone.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

via US Mail.

Correspondent Name: Haynes and Boone LLP Address Line 1: 2323 Victory Avenue

Address Line 2: Suite 700

Address Line 4: Dallas, TEXAS 75219

**PATENT** 

REEL: 028005 FRAME: 0434

P \$40.00 12/12665

501880412

ATTORNEY DOCKET NUMBER:	24061.1355/2009-0434
NAME OF SUBMITTER:	David M. O'Dell
Total Attachments: 3 source=1355-Assignment#page1.tif source=1355-Assignment#page2.tif source=1355-Assignment#page3.tif	

PATENT REEL: 028005 FRAME: 0435 Assignment

Docket No.: 2009-0434 / 24061.1355

Customer No.: 42717

#### ASSIGNMENT

W	<b>HER</b>	EA	S.	we.

(1)	Ying-Chou Cheng	of	7F-2, No. 21, Sec. 1, Jiafeng 11th Road Zhubei City, Hsinchu County 302, Taiwan, R.O.C.
(2)	Cheng-Lung Tsai	of	No. 28, 528 Alley, 640 Lane, Chung-San Road Hsin-Chu City, Taiwan, R.O.C.
(3)	Tsong-Hua Ou	of	4F, No. 76, Hualing Street, Shihlin District Taipei City 111, Taiwan, R.O.C.
(4)	Cheng Kun Tsai	of	14F-1, No. 10, Lane 107, Kesyueyuan Road Hsinchu City 300
(5)	Ru-Gun Liu	of	No. 9, Alley 19, Lane 452, Baoshan Road Hsinchu City 300, Taiwan, R.O.C.
(6)	Wen-Chun Huang	of	58, Zhong-Shan Road, Xi-Gang Village Xi-Gang Xiang, Tainan County 723, Taiwan R.O.C.

have invented certain improvements in

# METHOD, SYSTEM, AND APPARATUS FOR ADJUSTING LOCAL AND GLOBAL PATTERN DENSITY OF AN INTEGRATED CIRCUIT DESIGN

for which we have executed an application for Letters Patent of the United States of America, filed on February 25, 2010 and assigned application number February 25, 2010; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Page 1 of 3

R-243154\_1.DOC

Docket No.: 2009-0434 / 24061.1355

Customer No.: 42717

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:

Ying-Chou Cheng

Residence Address:

7F-2, No. 21, Sec. 1, Jiafeng 11th Road

Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: 2010/64/06

V Jing - Chon Chang Inventor Signature

Inventor Name:

Cheng-Lung Tsai

Residence Address:

No. 28, 528 Alley, 640 Lane, Chung-San Road

Hsin-Chu City, Taiwan, R.O.C.

Dated: 2010/04/01:

Chang-Lung Tsa;

Page 2 of 3

Assignment		Docket No.: 2009-0434 / 24061.1355 Customer No.: 4271	
Inventor Name:	Tsong-Hua Ou		
Residence Address:	4F, No. 76, Hualing Street, Shihlin District Taipei City 111, Taiwan, R.O.C.		
Dated: >>> (=)	104/02	Tsong - Hua Ou Inventor Signature	
Inventor Name:	Cheng Kun Tsai		
Residence Address:	14F-1, No. 10, Lane 107, Kesyueyuan Road Hsinchu City 300, Taiwan, R.O.C.		
Dated: >0 0/0	4 (02	Inventor Signature	
Inventor Name:	Ru-Gun Liu		
Residence Address:	No. 9, Alley 19, Lane 452, Baoshan Road Hsinchu City 300, Taiwan, R.O.C.		
Dated: Apr. 2.	, <b>~</b> /2	Ru-(zun L'un Inventor Signature	
Inventor Name:	Wen-Chun Huang		
Residence Address:	58, Zhong-Shan Road, Xi-Gan Xi-Gang Xiang, Tainan Count		

R-243154\_1.DOC

Page 3 of 3

Wen-Chun Iduang
Inventor Signature

**RECORDED: 04/06/2012**